RoHS

HALOGEN

FREE

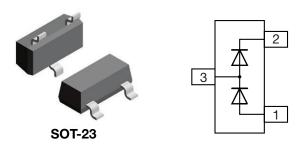
GREEN

(5-2008)



Vishay Semiconductors

Low Capacitance Rail to Rail Protection Diode in SOT-23



LINKS TO ADDITIONAL RESOURCES



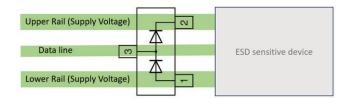






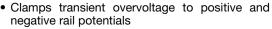


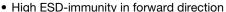
PRIMARY CHARACTERISTICS						
V_{RRM}	80 V					
C_D ; 1 MHz; $V_r = 0$ V: Pin 31 or 23	0.5 pF					
I _{PPM} (8/20 μs)	12 A					
ESD immunity (330 pF / 330 Ω)	± 30 kV					
T _J max.	150 °C					
Package	SOT-23					



FEATURES

- Low capacitance ESD-protection for one data line
- Low total capacitance C_{tot} = 1 pF





- 30 kV acc. ISO10605 (330 pF / 330 Ω)
- 30 kV acc. IEC61000-4-2 (150 pF / 330 Ω)
- AEC-Q101 qualified available
- Moisture sensitivity level (MSL) 1
- Molding compound meets UL 94 V-0 flammability rating
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

APPLICATIONS

- Telecommunication network
- Portable electronics
- Video Line Protection
- Microcontroller Input Protection
- I2C Bus Protection

The VR2RA1-03S is a low capacitance ESD-protection device for one data line with a working voltage between the two supply voltage levels (potential of the upper and lower rail) of the application.

As long as the voltage on the data line is within these two rail voltages both protection diodes of the VR2RA1-03S are reverse biased with a low leakage current and capacitance. Just when the voltage on the data line gets higher than the upper rail voltage or lower than the lower rail voltage one of the protection diodes gets in forward mode and clamps the transient voltage to the upper or lower rail voltage.

The low capacitance protection diode is made to conduct the surge current of a transient voltage spike in forward direction to the upper or lower rail. The maximum reverse voltage the diodes can withstand is 80 V. Higher reverse voltages can destroy the diodes. Therefore the impedance of the rail sources must be low enough to absorb the occurring surge current. Is this not given, the voltage between the two rails can be clamped by an unidirectional TVS diode.

ORDERING INFORMATION								
	ENVIRONMENTAL AND QUALITY CODE				PACKAG			
PART NUMBER (EXAMPLE)	AEC-Q101 QUALIFIED	RoHS-COMPLIANT + LEAD (Pb)-FREE TERMINATIONS	TIN PLATED	REVISION	3K PER 7" REEL (8 mm TAPE), 15K/BOX = MOQ	10K PER 13" REEL (8 mm TAPE), 10K/BOX = MOQ	ORDERING CODE (EXAMPLE)	
VR2RA1-03S	-	G	3	-	08		VR2RA1-03S-G3-08	
VR2RA1-03S	Н	G	3	-	08		VR2RA1-03SHG3-08	
VR2RA1-03S	-	G	3	-		18	VR2RA1-03S-G3-18	
VR2RA1-03S	Н	G	3	-		18	VR2RA1-03SHG3-18	



PACKAGE DATA RATINGS							
DEVICE NAME	PACKAGE NAME	TYPE CODE	WEIGHT	MOLDING COMPOUND FLAMMABILITY RATING	MOISTURE SENSITIVITY LEVEL	SOLDERING CONDITIONS	
VR2RA1-03S	SOT-23	R2R	9.2 mg	UL 94 V-0	MSL level 1 (according J-STD-020)	Peak temperature max. 260 °C	

PARAMETER	TEST CONDITION	SYMBOL	VALUE	UNIT
Repetitive peak reverse voltage		V_{RRM}	80	V
Peak forward surge current	t _p = 8.3 ms, sine half wave	I _{FSM}	2	Α
Peak forward surge current	t _p = 100 μs	I _{FSM}	4	Α
Peak forward surge current	t _p = 10/1000 μs, acc. Fig.3	I _{FSM}	4	Α
Peak forward surge current	t _p = 8/20 μs, acc. Fig.2		12	Α
Peak forward surge current	t _p = 100 ns, (TLP)	I _{FSM}	60	Α
Average forward current	Half wave rectification with resistive load and f ≥ 50 Hz mounted on Infinite heatsink	I _{F(AV)}	250	mA
Forward current	mounted on Infinite heatsink	I _F	350	mA
Power dissipation	on FR-4 board with recommended soldering footprint	P _{tot}	270	mW
Thermal resistance junction to ambient air	tance junction to ambient air according to JEDEC® 51-3 on FR-4 board with recommended soldering footprint		460	K/W
Thermal resistance junction to lead	mounted on Infinite heatsink	R _{thJL}	320	K/W
Junction temperature		Tj	150	°C
Storage temperature range		T _{stg}	-65 to +150	°C
Operating temperature range		T _{op}	-55 to +150	°C
ESD Immunity	forward direction (pin 1 to 3 or 3 to 2) acc. ISO10605 (330 pF/ 330 Ω) IEC61000-4-2 (150 pF/330 Ω)	V _{ESD}	30	kV

ELECTRICAL CHARACTERISTICS (T _{amb} = 25 °C, unless otherwise specified)								
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT		
Forward voltage	I _F = 1 mA	V_{F}	ı	-	0.75	V		
Reverse current	$V_{R} = 80 \text{ V},$	I _R	-	12	30	nA		
Reverse current	$V_R = 80 \text{ V}, T_j = 150 ^{\circ}\text{C}$	I _R	-	-	30	μA		
Reverse breakdown voltage	I _R = 20 μA	V_{BR}	100	-	-	V		
Diode capacitance	$V_R = 0$, f = 1 MHz; Pin 1 to 3 or 3 to 2	C_D	-	0.5	0.6	pF		
Total capacitance	$V_R = 0$, $f = 1$ MHz; Pin 1+2 to 3	C_{tot}	-	1	1.2	pF		

TYPICAL CHARACTERISICS (T_{amb} = 25 °C, unless otherwise specified)

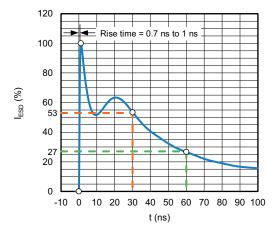


Fig. 1 - ESD Discharge Current Wave Form acc. IEC 61000-4-2 (330 Ω / 150 pF)

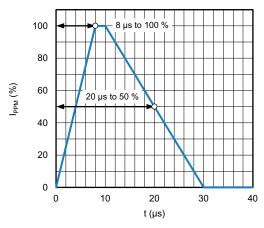


Fig. 2 - 8/20 µs Peak Pulse Current Wave Form acc. IEC 61000-4-5

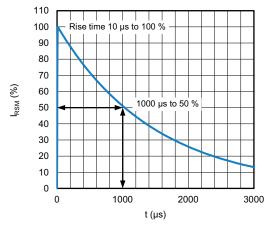


Fig. 3 - 10/1000 µs Peak Pulse Current Wave Form

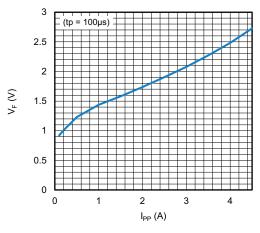


Fig. 4 - Typical Peak Forward Clamping Voltage vs. Peak Pulse Current; $t_p = 100~\mu s$

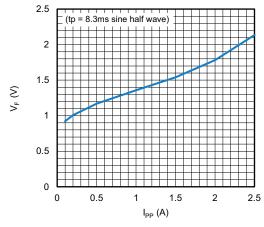


Fig. 5 - Typical Peak Forward Clamping Voltage vs. Peak Pulse Current; $t_p = 8.3 \text{ ms}$

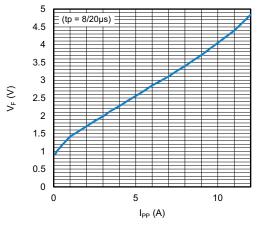


Fig. 6 - Typical Peak Forward Clamping Voltage vs. Peak Pulse Current; $t_p = 8/20~\mu s$



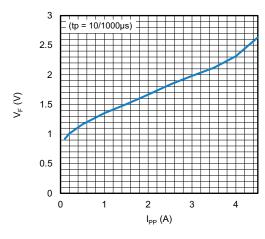


Fig. 7 - Typical Peak Forward Clamping Voltage vs. Peak Pulse Current; $t_p = 10/1000~\mu s$

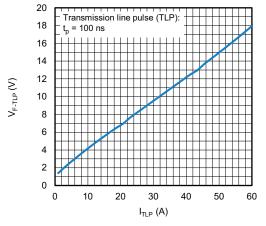


Fig. 8 - Typical Peak Forward Clamping Voltage vs. Peak Pulse Current; $t_p = 100$ ns (TLP)

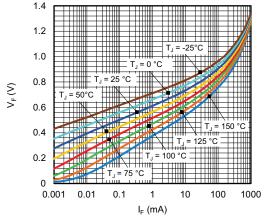


Fig. 9 - Typical Forward Voltage vs. Forward Current

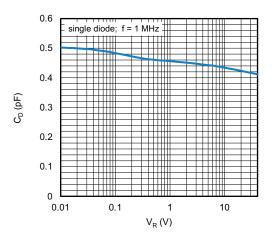


Fig. 10 - Typical Capacitance vs. Reverse Voltage

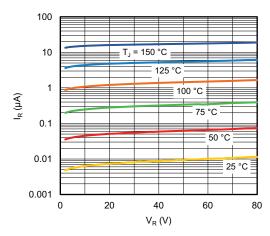


Fig. 11 - Typical Reverse Leakage Current vs. Reverse Voltage

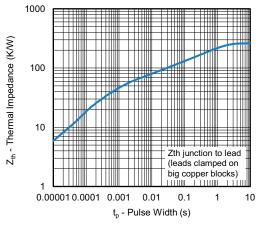
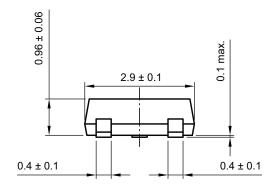
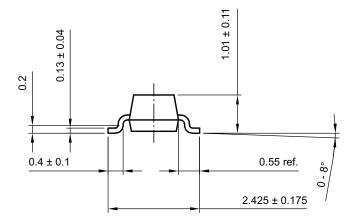
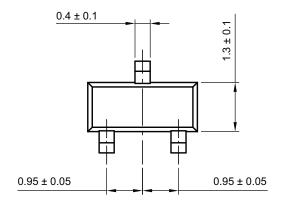


Fig. 12 - Thermal Impedance vs. Time

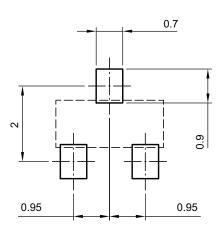
PACKAGE DIMENSIONS in millimeters: **SOT-23**







footprint recommendation:



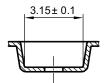
Created - Date: 18-Oct-2021 Rev. 01 - Date: 18-Jan-2022 S8-V-3929.01-009 (4)



CARRIER TAPE SOT-23

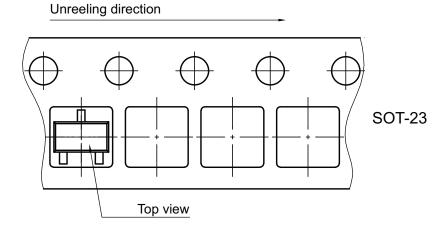
A-A Section 0.229 ± 0.013 0.229 ± 0.013 0.229 ± 0.013 0.229 ± 0.013

B-B Section



Created Date: 04-Feb-2010 Rev. Date: 07-Feb-2022 S8-V-3929.01-005 (4)

ORIENTATION IN CARRIER TAPE SOT-23



Created Date: 04-Feb-2010 Rev. Date: 07-Nov-2022 S8-V-3929.01-005 (4)



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